

TOSHIBA High Efficiency Rectifier Silicon Epitaxial Type

# CMH08A

## Switching Mode Power Supply Applications

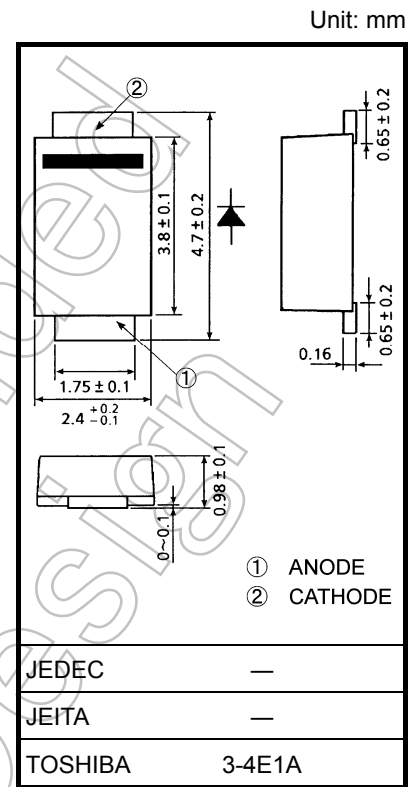
- Repetitive peak reverse voltage:  $V_{RRM} = 400\text{ V}$
- Average forward current:  $I_F (AV) = 2.0\text{ A}$
- Low forward voltage:  $V_{FM} = 1.8\text{ V (Max.)}$
- Very Fast Reverse-Recovery Time:  $t_{rr} = 35\text{ ns (Max.)}$
- Suitable for compact assembly due to small surface-mount package "M-FLAT™" (Toshiba package name)

## Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

| Characteristics                                       | Symbol     | Rating       | Unit             |
|---|------------|--------------|------------------|
| Repetitive peak reverse voltage                       | $V_{RRM}$  | 400          | V                |
| Average forward current                               | $I_F (AV)$ | 2.0 (Note 1) | A                |
| Peak one cycle surge forward current (non-repetitive) | $I_{FSM}$  | 20 (50 Hz)   | A                |
| Junction temperature                                  | $T_j$      | -40~150      | $^\circ\text{C}$ |
| Storage temperature range                             | $T_{stg}$  | -40~150      | $^\circ\text{C}$ |

Note 1:  $T_l = 99^\circ\text{C}$  Device mounted on a ceramic board  
 board size: 50 mm × 50 mm  
 soldering land: 2 mm × 2 mm  
 board thickness: 0.64t

Note 2: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).



## Electrical Characteristics ( $T_a = 25^\circ\text{C}$ )

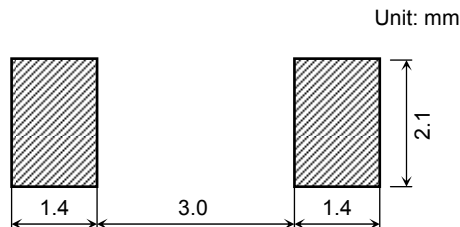
| Characteristics                          | Symbol         | Test Condition   | Min | Typ. | Max | Unit                      |
|--|----------------|--|-----|------|-----|---------------------------|
| Peak forward voltage                     | $V_{FM} (1)$   | $I_{FM} = 0.1\text{ A}$ (pulse test)   | —   | 0.88 | —   | V                         |
|  | $V_{FM} (2)$   | $I_{FM} = 1.0\text{ A}$ (pulse test)   | —   | 1.3  | —   |                           |
|  | $V_{FM} (3)$   | $I_{FM} = 2.0\text{ A}$ (pulse test)   | —   | 1.6  | 1.8 |                           |
| Peak repetitive reverse current          | $I_{RRM}$      | $V_{RRM} = 400\text{ V}$ (pulse test)  | —   | —    | 10  | $\mu\text{A}$             |
| Reverse recovery time                    | $t_{rr}$       | $I_F = 1\text{ A}$ , $di/dt = -30\text{ A}/\mu\text{s}$  | —   | —    | 35  | ns                        |
| Forward recovery time                    | $t_{fr}$       | $I_F = 1.0\text{ A}$   | —   | —    | 100 | ns                        |
| Thermal resistance (junction to ambient) | $R_{th} (j-a)$ | Device mounted on a ceramic board (board size: 50 mm × 50 mm) (soldering land: 2 mm × 2 mm) (board thickness: 0.64 t)        | —   | —    | 60  | $^\circ\text{C}/\text{W}$ |
|  |                | Device mounted on a glass-epoxy board (board size: 50 mm × 50 mm) (soldering land: 6 mm × 6 mm) (board thickness: 1.6 t)     | —   | —    | 135 |                           |
|  |                | Device mounted on a glass-epoxy board (board size: 50 mm × 50 mm) (soldering land: 2.1 mm × 1.4 mm) (board thickness: 1.6 t) | —   | —    | 210 |                           |
| Thermal resistance (junction to lead)    | $R_{th} (j-t)$ | —  | —   | —    | 16  | $^\circ\text{C}/\text{W}$ |

Start of commercial production  
2002-12

## Marking

|           |             |
|-----------|-------------|
| Type code | Product No. |
| H8        | CMH08A      |

## Standard Soldering Pad



## Handling Precaution

The absolute maximum ratings mean the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The followings are the general derating method that we recommend when you design a circuit with a device.

VRRM: We recommend that the worst case voltage, including surge voltage, be no greater than 80% of the absolute maximum rating of VRRM for a DC circuit and be no greater than 50% of that of VRRM for an AC circuit.

VRRM has a temperature coefficient (0.1%/°C). Please consider this temperature coefficient when you design a device at low temperature.

IF(AV): We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF(AV).

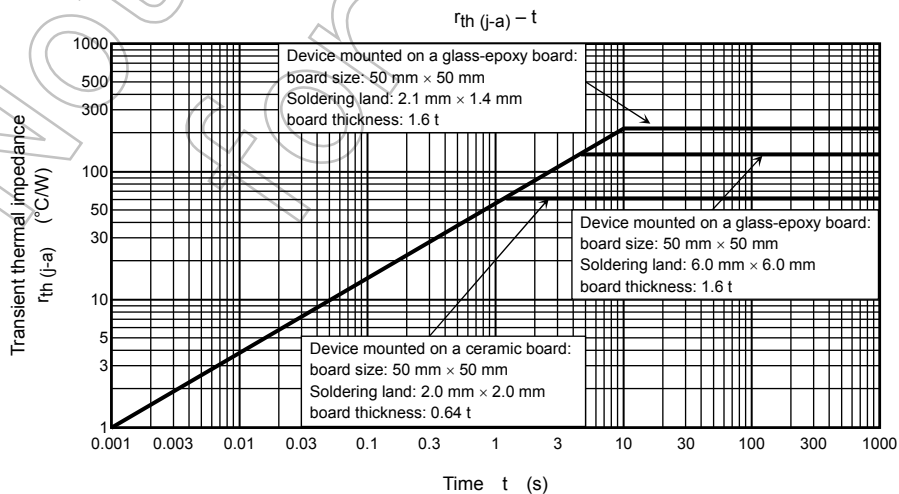
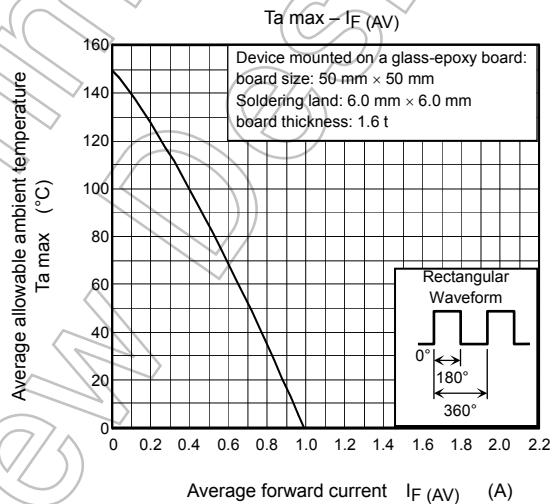
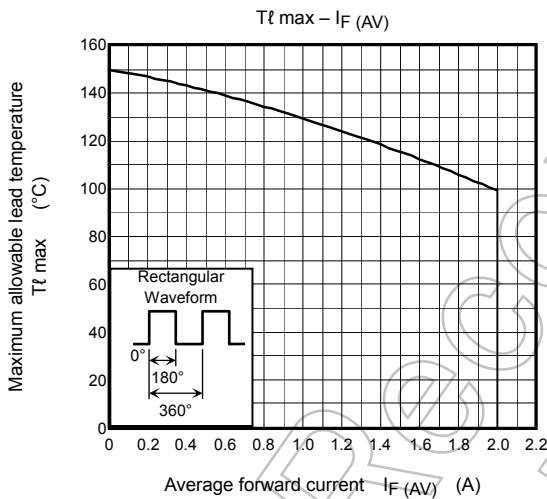
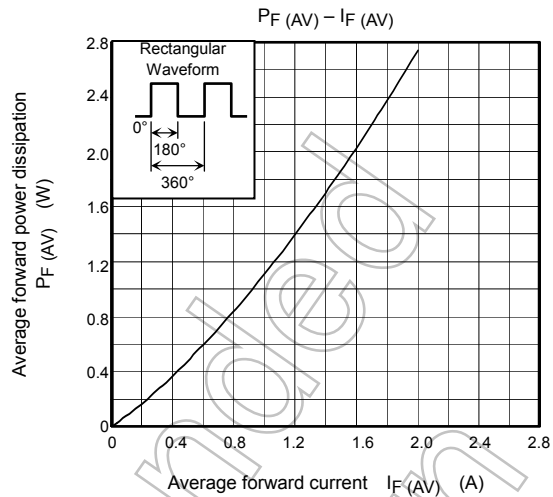
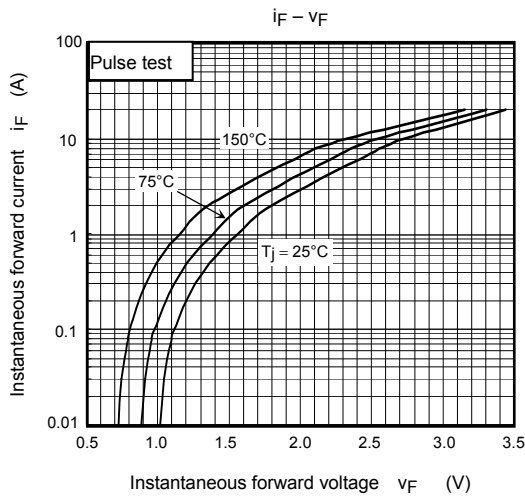
Please do the sufficient heat design. If you can't design a circuit with excellent heat radiation, please set a margin by using an allowable Tamax-IF (AV) curve.

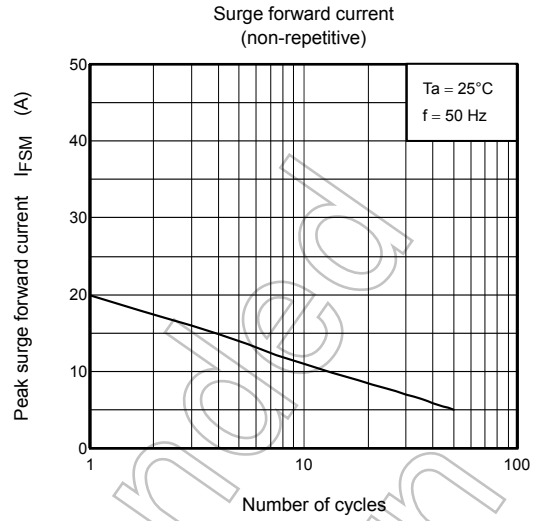
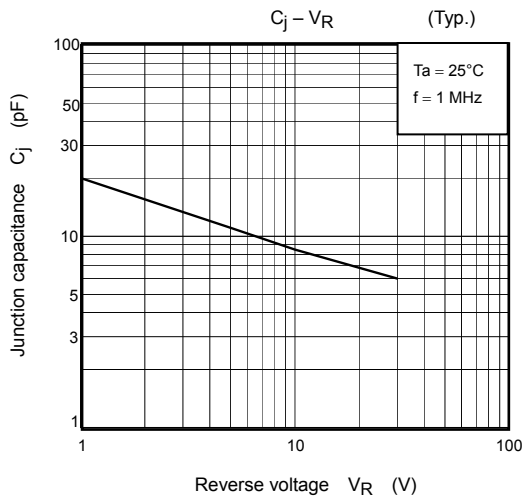
This rating specifies the non-repetitive peak current in one cycle of a 50-Hz sine wave, condition angle 180°. Therefore, this is only applied for an abnormal operation, which seldom occurs during device's lifespan.

We recommend that a device be used T<sub>j</sub> of below 120°C under the worst load and heat radiation conditions.

Thermal resistance between junction and ambient fluctuates depending on device's mounting condition. When using a device, please design a circuit board and a soldering land size to match the appropriate thermal resistance value.

Please refer to Rectifier databook for further information.





Not Recommended for New Design

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